

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L2	48583	CMP or "chemical mechanical polishing"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:42
2	BRS	L3	200874 6	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:42
3	BRS	L4	11062	"polishing pad"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:42
4	BRS	L5	12403	remov\$6 adj rate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:42
5	BRS	L6	1760	conditioning near4 pad	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:43

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L7	1174125	calculate ot calculated or calculating	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:44
7	BRS	L8	2396721	rotate or rotating or rotated	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:44
8	BRS	L9	491	2 and 3 and 4 and 5 and 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 11:46
9	BRS	L10	95	9 and 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 12:26
10	IS&R	L11	1136	(438/689).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 12:26

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	IS&R	L12	650	(438/691).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 12:26
12	IS&R	L13	1906	(438/692).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/08/20 12:26